
Radiation Tolerant RISC-V processor and SoC platform

Implementing DRD7: an R&D Collaboration on
Electronics and On-detector Processing.

2nd workshop

25 September 2023

Kostas Kloukinas



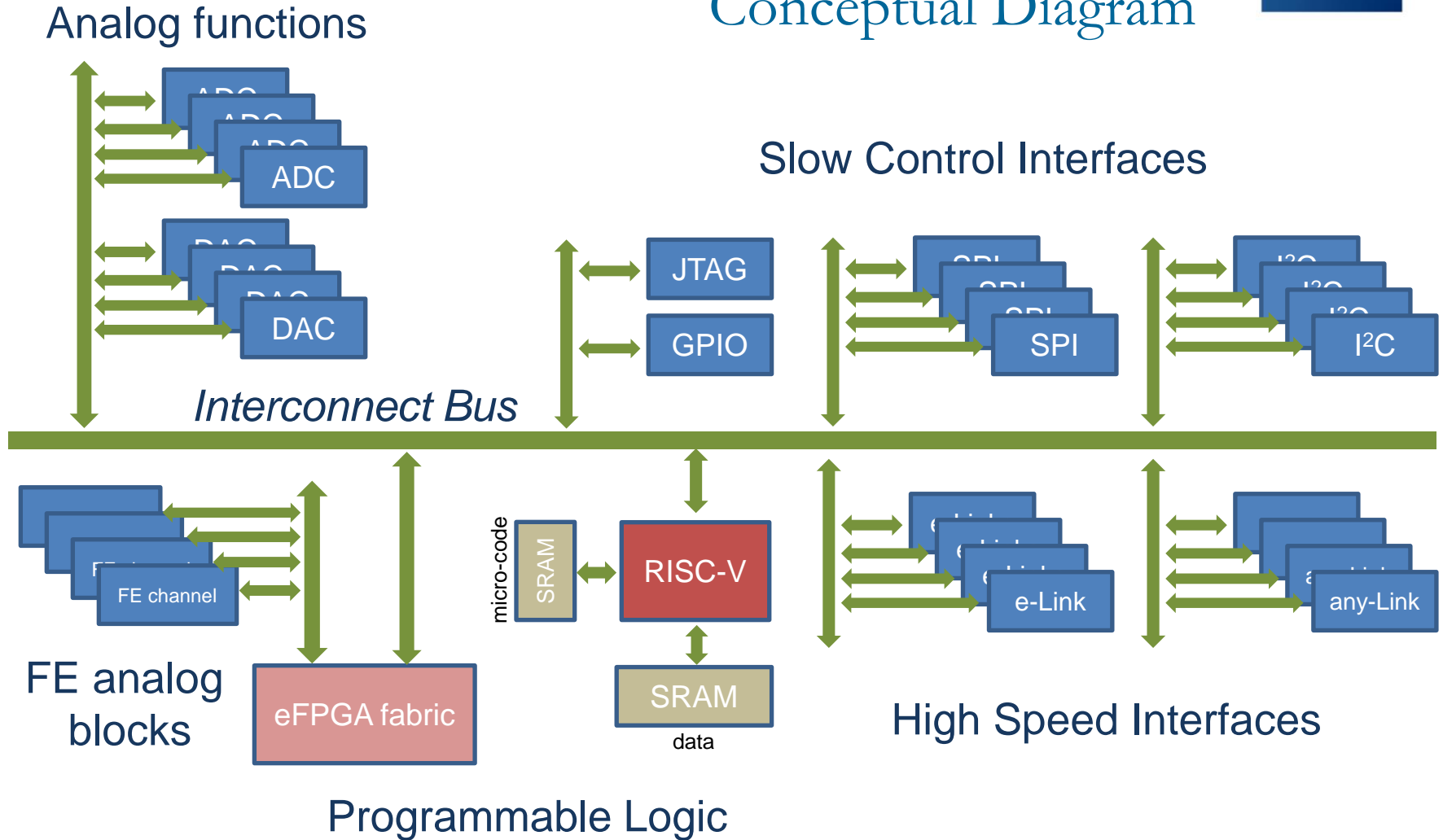
Introduction

- Project intentions
 - Rad-Tol RISC-V based System-on-Chip design
- Participating institutes, as of today
(in order of presentations)
 - CERN
 - KU LEUVEN
 - Fachhochschule Dortmund
 - UK Consortium

- **EP-R&D WP5.2 Rad-Tol SoC Ecosystem activity**
 - Motivation
 - Tackle design complexity in future experiments
 - Control development cost on advanced nodes
 - Facilitate on-detector “intelligence”
 - Enable reconfigurable, retargetable FE ASICs

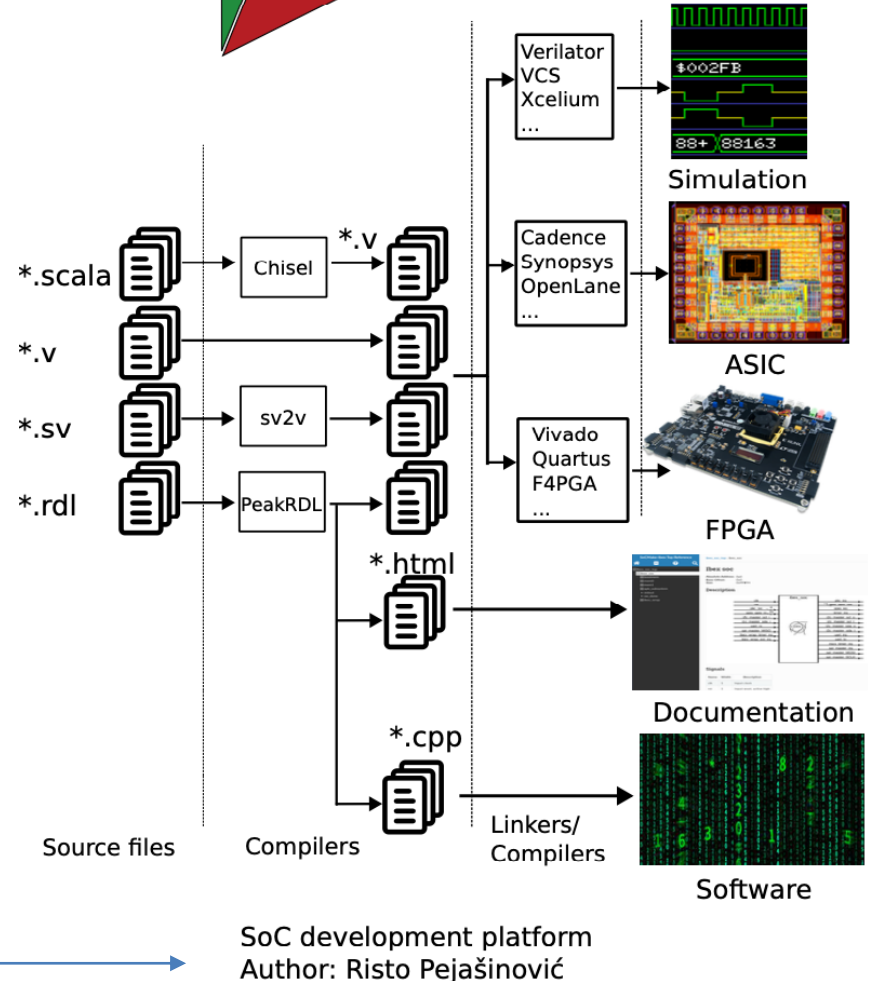
 - Propose a SoC ASIC design methodology
 - Introduce an abstract design methodology
 - Develop reusable IP blocks
 - Standardized interconnects for IP blocks
 - Replace state machines with a control processor (RISC-V based)
 - Programmable, flexible logic blocks (SoC Ecosystem, cores, eFPGA, NoCs)
 - Enhance Hierarchical Digital Implementation and Verifications

Conceptual Diagram



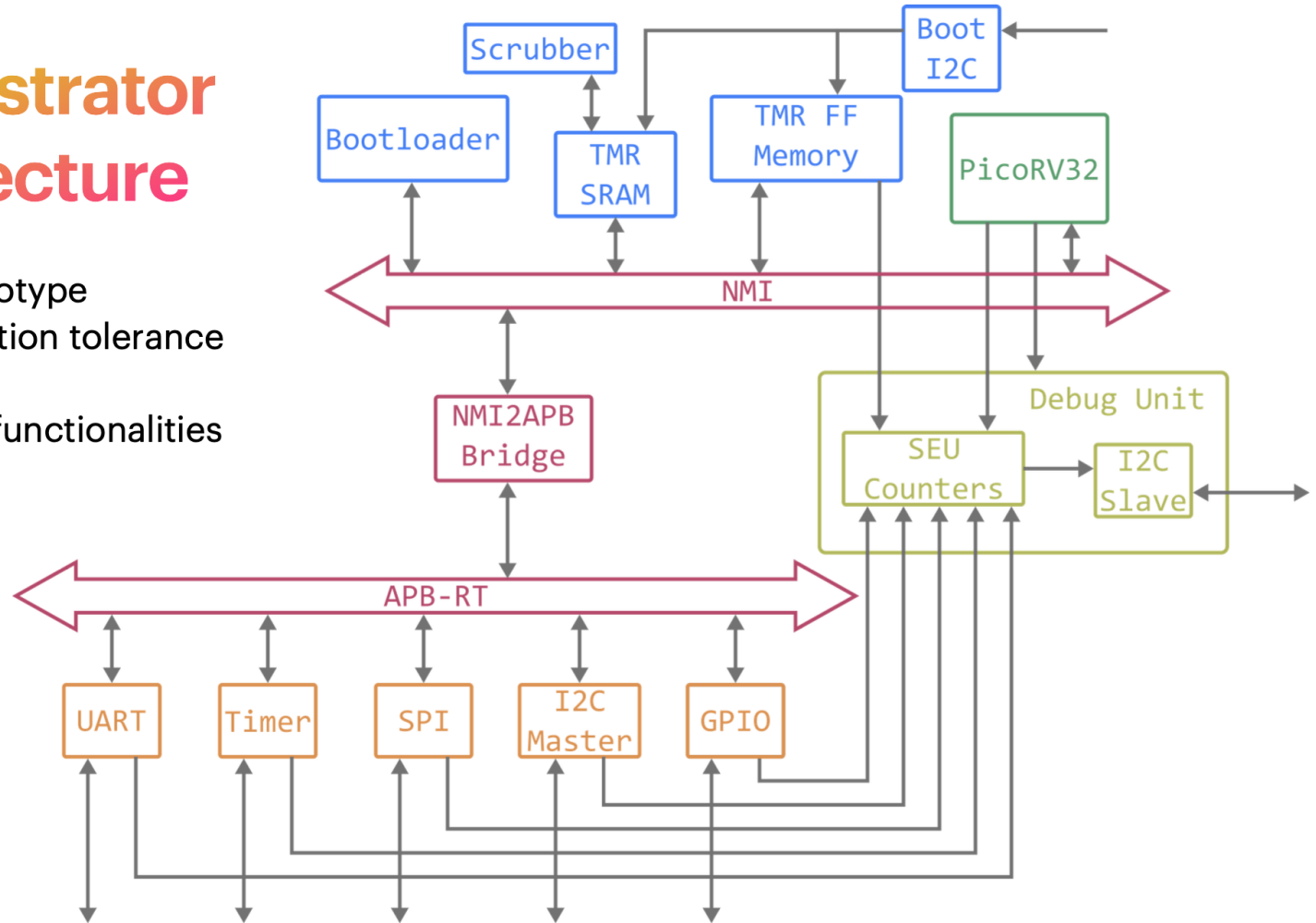


- SoCMake
 - SoC generator tool
 - *SystemRDL* language to automatize the generation of:
 - Hardware design
 - Software toolchain
 - Verification platform
 - Documentation
 - Generate custom SoCs
 - Rapid SoC prototyping
 - Work in progress



Demonstrator architecture

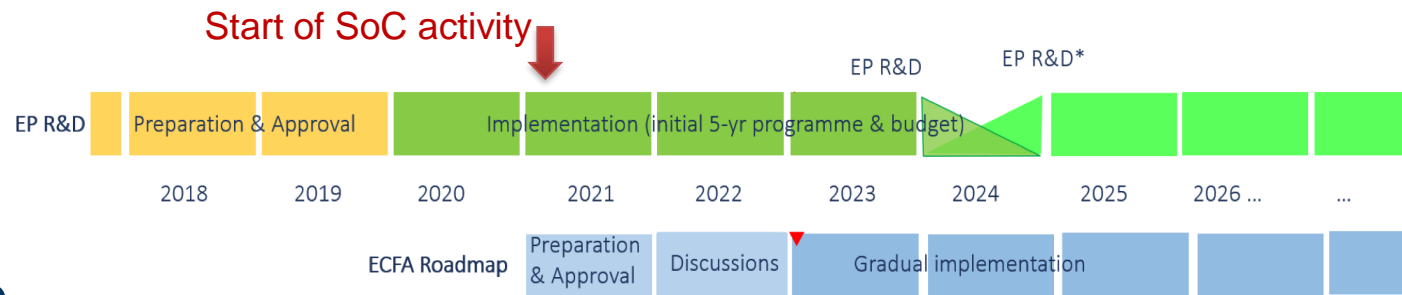
- First ASIC prototype
- Focus on radiation tolerance testability
- Limited set of functionalities



Alessandro Caratelli
 Marco Andorno
 Anvesh Nookala
 Davide Ceresa
 Risto Pejasinovic

■ Timeline

- ❑ SoC activity started in 2021, during EP R&D phase I
- ❑ Approved to continue in phase II, for *at least* four more years



■ Scope

- ❑ Open platform for Rad-Tol SoC ASIC design
- ❑ SoC & core architecture, Verification, Implementation

■ Resources

- ❑ 1 fellow, 2 students, 3 part-time staff

DRD7 Workshop

Radiation Tolerant RISC-V Processors

Levi Mariën
Electronic Circuits and Systems (ESAT)
Advanced Integrated Sensing Lab (ADVISE)

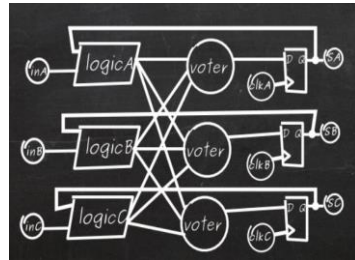


Motivation behind our research

- Spatial redundancy techniques
 - TMR, DMR, dual lockstep systems, ...



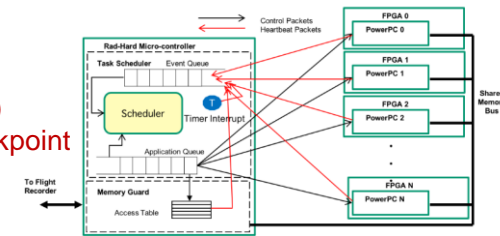
- Simple to understand
- Reliability failure reduces by orders of magnitude
- Can be automatized
- Large area and power overhead (> 2x/3x)
- difficult to implement (RTL and physical constraints)



- Radiation hardening by software techniques
 - Instruction replay or checkpoint recovery



- Low area overhead
- Low critical path delay overhead
- Can be fully implemented in software
- Significantly complicates the software stack
- Performance loss (lost cycles)
- Memory requirement for checkpoint recovery



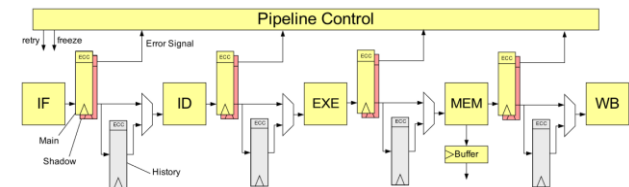
- Pipeline rollback
 - Register encoding/decoding
 - Pipeline rollback when non-recoverable error occurs



- Low area overhead
- Can mitigate SETs and SEUs

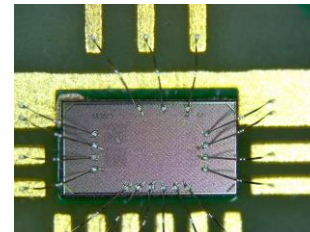
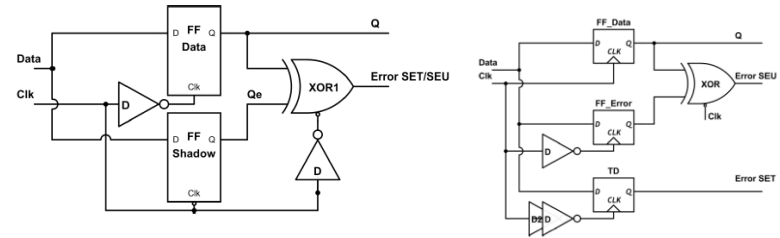


- Increases critical path delay
- Latency penalty when rollback
- Complex to implement

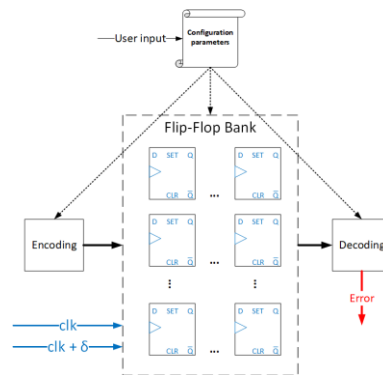
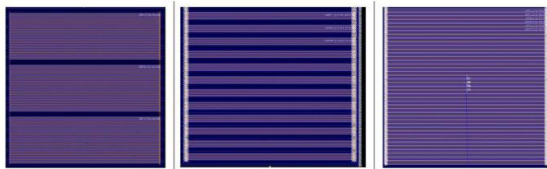


In-situ SEE error detection and correction

- Single-Event Effect (SEE) error detection
 - Double sampling error detection flip-flop
 - Parallel error detection flip-flop
 - Test chip created
- Single-Event Effect (SEE) error correction
 - Fully configurable



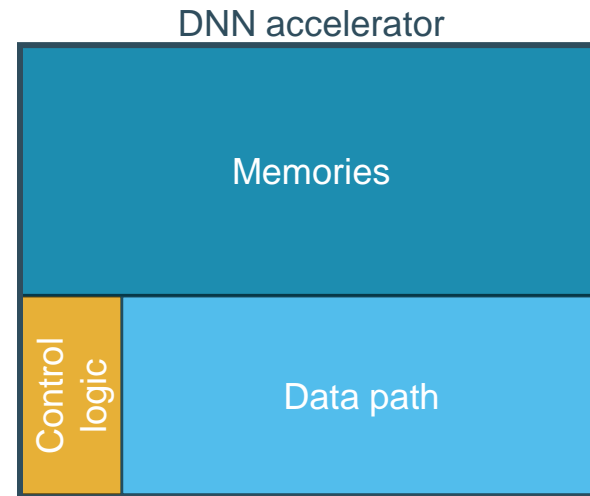
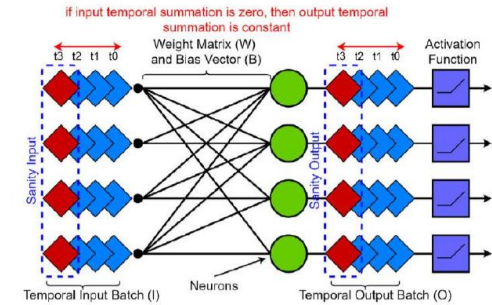
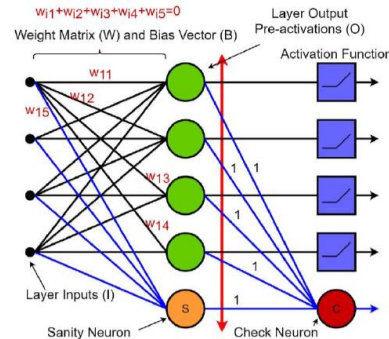
σ (cm ²)	Parallel EDFFF	Double Sampling EDFFF
σ_{SET}	1.6×10^{-8}	N/A
σ_{SEU}	7.4×10^{-8}	4.6×10^{-8}
σ_{data}	1.3×10^{-8}	1.1×10^{-8}
False Negative	0.12×10^{-8}	0
False Positive	7.9×10^{-8}	3.5×10^{-8}



	EDFF 1	EDFF 2	DFF	TMR	Glitch
Static Power (nW)	5.5	3.4	1.4	11.1	5.2
Dynamic Power (fJ)	4.3	4.9	1.6	8.4	5.5
Propagation Delay (ps)	65.5	65.4	62.5	103	568
Area (μm^2)	12.3	8.9	3.1	10.1	10.8

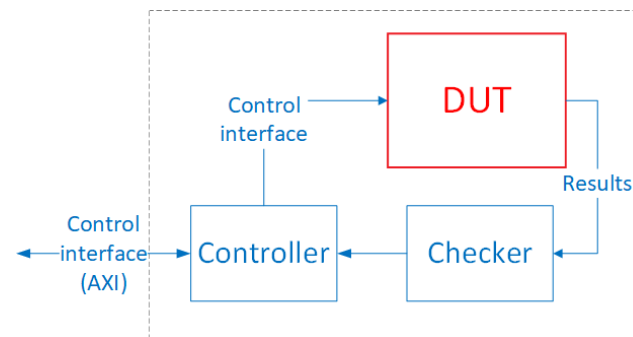
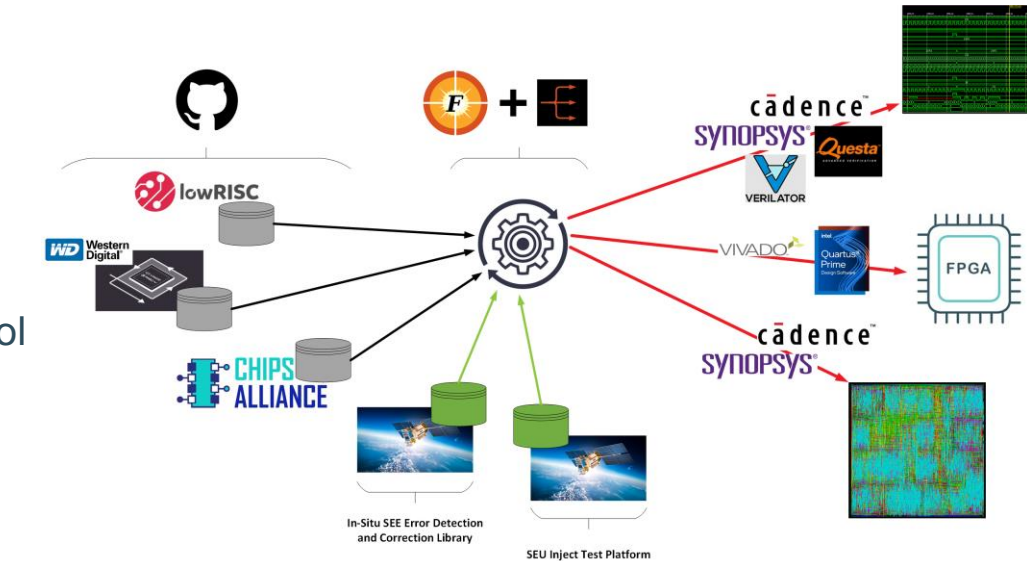
SEE mitigation in DNN accelerators

- Memories: 50-70% area
 - SEC-DED code to harden
- Data path: 30-50% area
 - Software/hardware mitigation
 - Software-based DNN tolerance
 - Hardware checker neurons
- Control logic: 2-5% area
 - TMR



Long term goal

- Any RISC-V core can be targeted
 - Hell, any design for that matter
- Fueled by FuseSoC and Edalize
 - Achieving the power of vendor and tool independence
- In-Situ SEE error detection and correction library
- SEU inject test platform
 - In simulation testing
 - At runtime (FPGA) testing
 - Formal verification?



Contributions and resources

- Contributions
 - Rad-hard RISC-V SoC development on TSMC 28nm HPC+ or 22nm FDSOI technology
- Resources
 - 5 person team for 3 years
 - 3 persons already funded
 - 3 * 3FTE, resources already available
 - 2 persons to be funded
 - 2 * 3 FTE, resources considering asking

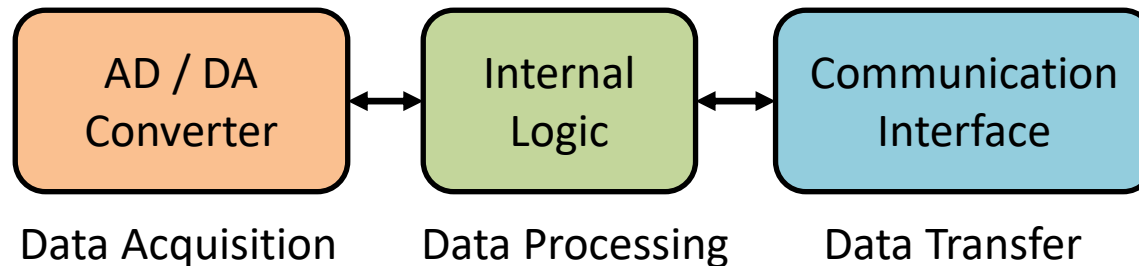
A radhard RISC-V microcontroller implementation

25.09.2023

2nd DRD7 workshop
Michael Karagounis

- First thoughts about the usefulness of a radiation-hard μC arose during the development of the MOPS (Monitoring of Pixel) chip
 - MOPS digitizes pixel module voltage and temperature and communicates via CANOpen
 - CANOpen is usually implemented in software but was implemented in hardware for MOPS

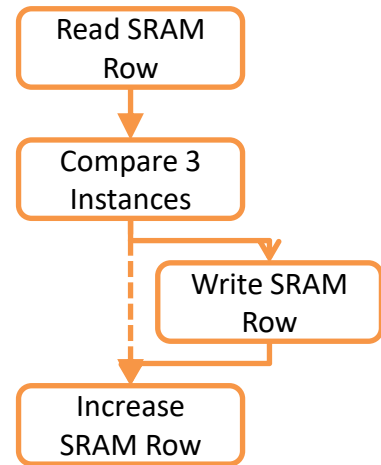
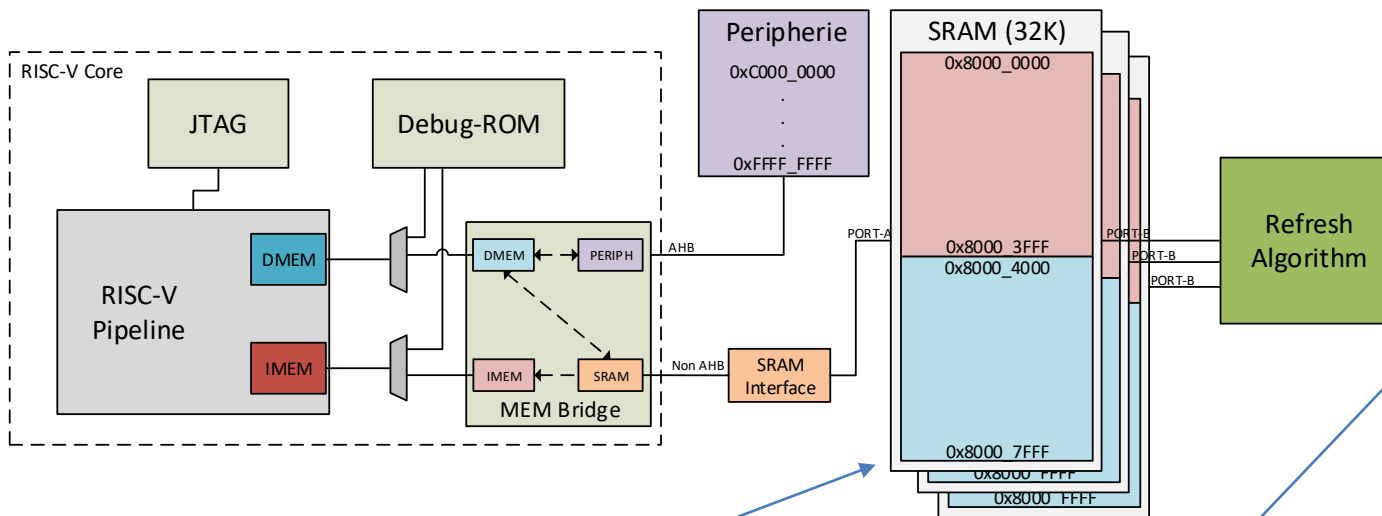
- Many custom ASICs have a similar structure:



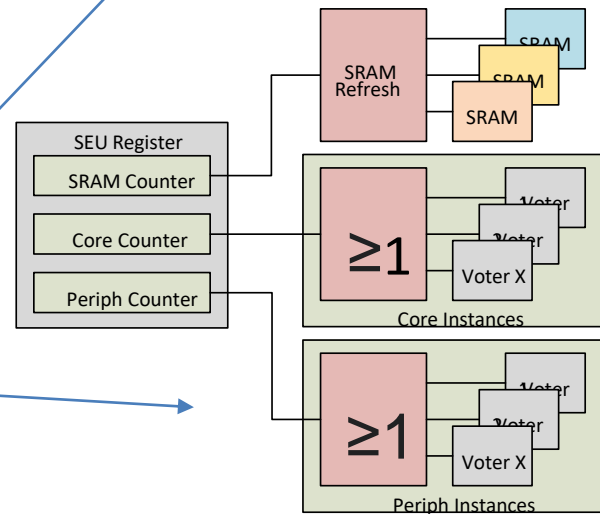
- Design of hardwired custom ASIC is complex and time consuming
 - Big verification effort
 - Bugfixes detected in silicon need redesign and new production cycle
- Adaptation to new projects is difficult
 - hardwired logic needs full redesign
- **Idea:** replace internal data processing logic with radiation-hard RISC-V core
 - Adaptation to new application and bugfixes via software updates

Design of TMR protected RISC-V microcontroller

- Fully TMR protected RV32-IMC Core designed in TSMC 65nm
 - 3 stage pipeline with multiplication and compressed instruction set extension
- 1.2V Core & I/O supply and 50 MHz clock

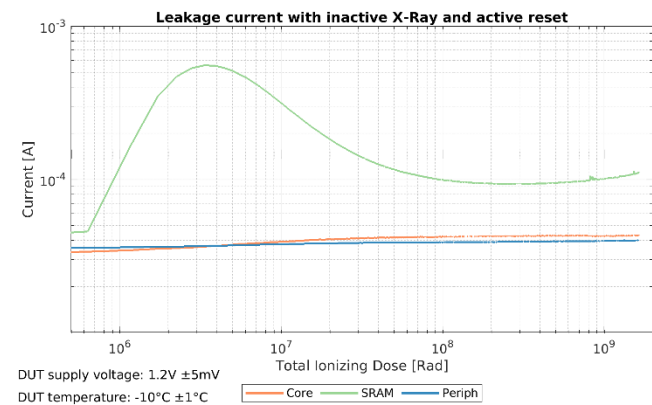
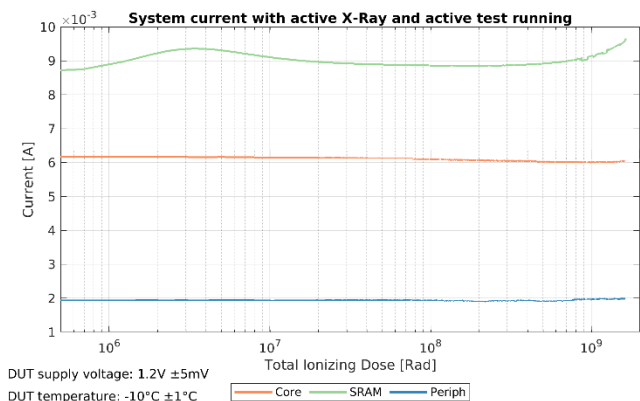


- three SRAM instances protected with scrubbing algorithm
- SEU detection & counting logic

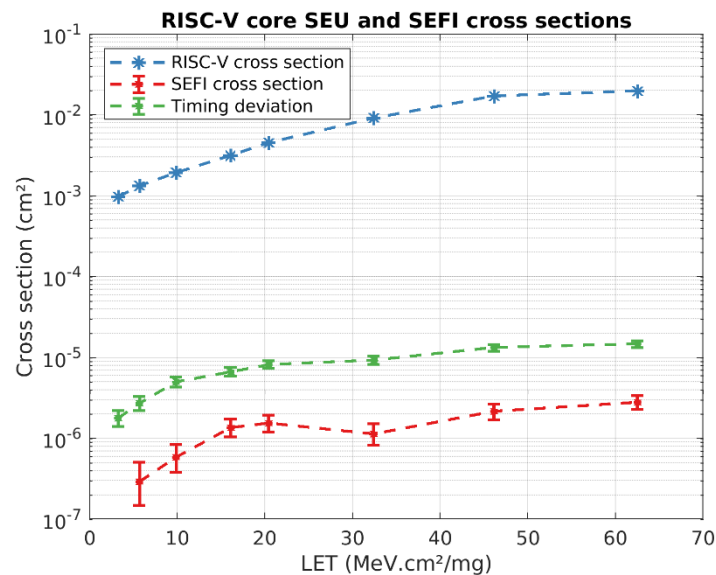


TID & SEE Characterization

- X-ray irradiation at -20°C
- TID of 1 Grad reached
- SRAM leakage current main driver of increased current consumption



- Heavy ion irradiation for study of SEE



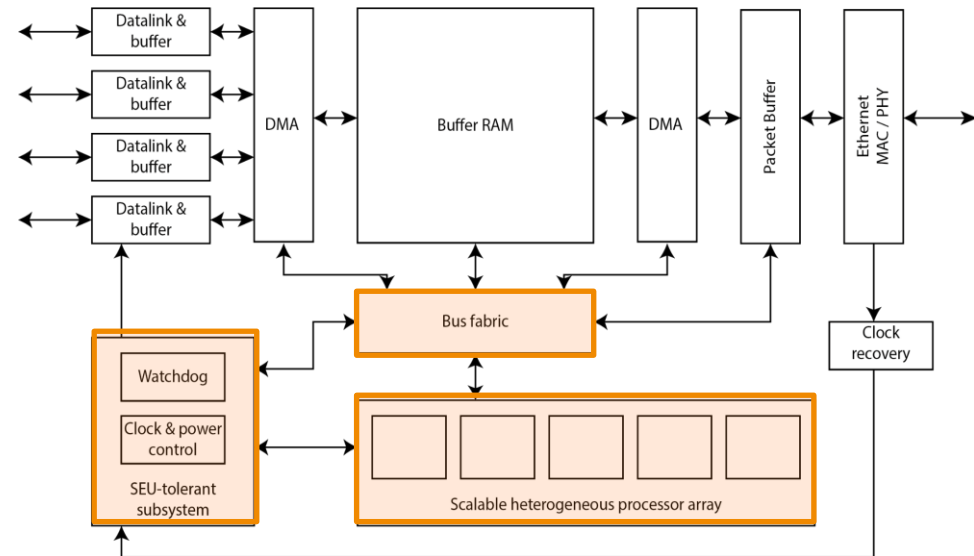
- cross section of corrected SEUs extracted by SEU counter circuit
- SEFI cross section is three orders of magnitude smaller than SEU cross section

A. Walsemann, M. Karagounis, A. Stanitzki, D. Tutsch, **A radiation hard RISC-V microprocessor for high-energy physics applications**, Nuclear Instruments and Methods in Physics Research Section A, vol. 1056, p. 168633, 2023

- Overall project goal is an open-source Zero SEFI microcontroller at LHC inner layer SEE rates
 - Are there additional architecture level protection measures necessary apart from TMR?
- Development of a well-elaborated verification suite
 - Verification of functionality and TMR implementation
 - study of cycle accurate golden models and/or virtual prototypes
- Improve diagnose capability during SEE radiation testing
 - Not only detect SEFIs but also cause of SEFIs
- Resources
 - 0.67 FTE (PhD student) for 1+3 years
 - Funds for Submission of chip prototypes

UK Consortium Contribution

- **UK (STFC) Consortia**
 - Royal Holloway, Birmingham, Warwick, Bristol, Manchester, RAL.
- **Motivation**
 - Develop common interface ASIC to couple a range of specialised FE ASICs to a common industry-standard off-detector interface.
- **Plans for DRD7.2.b**
 - Study/design of processor
 - Verification/testing of cores
 - Evaluate SoC platform
 - Software Ecosystem
- **Contribution**
 - Q4 2023: requests for funds
 - >1 FTE for 4 years



Proposed common interface ASIC for detector readout, timing, and control



Towards a Project Proposal

- Develop a Rad-Tol RISC-V based SoC ASIC design platform for HEP experiments
 - Standardized Architectures
 - Implementation Methodologies
 - Verification Methodologies
 - IP block Repository
 - Propose standardized solutions to the HEP community

- Establish regular meetings
 - Kick-off meeting in late October 2023
 - Identify areas of expertise
 - Define fields of contribution

- Finalize Project Proposal

A nighttime photograph of the Globe of Science and Innovation at CERN. The globe is illuminated from within, showing its metallic structure. The background is a dark blue night sky with stars and a bright meteor streaking across the right side.

Thank You